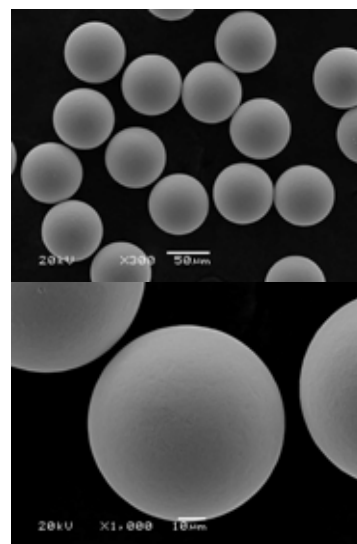


**SHENMAO Exhibits at ECTC in Las Vegas June 1-2, 2016 Booth # 505**  
**Introduces BGA and Micro BGA Solder Spheres**



SHENMAO BGA Solder Spheres for PBGA, CBGA, TBGA, CSP and Flip Chip Assemblies are made by UMT (Ultra Micron Technology) from highly pure metals produced to various exact Alloy compositions using Piezoelectric Droplet Jet Technology in high volumes to accurate diameter uniformity, bright shiny surface finishes and high quality sphericity. Various diameters (0.75, 0.6, 0.5, 0.45, 0.3, 0.25, 0.1, 0.08, 0.07, 0.06 and 0.05 mm Dia.) are available at affordable low cost from 8 worldwide SHENMAO locations.

SHENMAO High Drop-Resistance Alloy PF902-S (SAC0307X) greatly increases reliability and performance of Portable Electronic Devices drop test.

As the World's Major Solder Materials Provider, SHENMAO produces SMT Solder Paste, Wave Solder Bar, Solder Wire and Flux, Solder Preforms, Semiconductor Packaging Solder Spheres, Wafer Bumping Solder Paste, Dipping Flux and PV Ribbon.

For more information, please contact:

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